

Abstract

Method for Simultaneously Cutting a Compound Rod of Semiconductor Material into a Multiplicity of Wafers

Method for simultaneously cutting a compound rod of semiconductor material into a multiplicity of wafers by means of a wire saw, comprising the following steps:

- a) selecting at least two workpieces from a stock of workpieces, which have been cut from one or more semiconductor rods;
- b) grinding at least one of the two end surfaces of each rod;
- c) cementing the at least two workpieces together on their ground end surfaces by using a fastening means, to produce a compound rod piece and fixing the compound rod piece in the longitudinal direction on a mounting plate, there respectively being only a distance between the workpieces due to the fastening means located between them;
- d) clamping the mounting plate with the compound rod piece fixed thereon in the wire saw; and
- e) cutting the compound rod perpendicularly to its longitudinal axis by means of the wire saw.

Fig. 1